

SF2143B

- Designed for SDARS IF
- SAW Diplexer 72.54 MHz / 80.46 MHz
- 5.0 X 7.0 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)



Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any Two Terminals	0	VDC
Operating Temperature Range	-40 to +105	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Peak Solder Reflow Temperature, 10 seconds/5 cycles	260	°C

72.54 / 80.46 MHz **SAW Diplexer**



SMP-03

Electrical Characteristics TDM1 Filter

Characteristic			Notes	Min	Тур	Max	Units
Nominal Center Frequency		f _C			72.54	•	MHz
Passband Width:	1 dB	BW ₁	1	3.7	4.1		MHz
	15 dB	BW ₁₅	'		6.4	6.7	MHz
	30 dB	BW ₃₀			7.3	7.5	MHz
Passband Minimum Insertion Loss (including matching	network) at f _C	IL _{MIN}			16	18	dB
Amplitude Ripple, f _C ± 1.85 MHz					0.6	1.3	dB _{P-P}
Attenuation Relative to Minimum Insertion Loss:	50.00 to 66.48 MHz			40	42		dB
	66.48 to 68.08 MHz			37	42		dB
	77.30 to 78.60 MHz			30	33		dB
	78.60 to 86.50 MHz			30	33		dB
	86.50 to 91.50 MHz			39	43		dB
	91.50 to 100.0 MHz			42	46		dB
Group Delay Ripple					30	150	ns _{P-P}
Source Impedance, Differential				27	ohms or 200 oh	ms	
Load Impedance, Differential				1K	ohms or 1.5K of	nms	İ

Electrical Characteristics TDM2 Filter

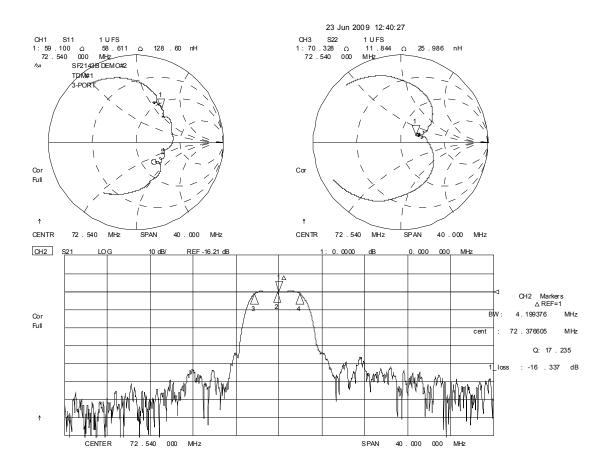
Characteristic		Sym	Notes	Min	Тур	Max	Units
Nominal Center Frequency		f _C		80.46		MHz	
Passband Width:	1 dB	BW ₁	1	3.7	4.2		MHz
	15 dB	BW ₁₅	1 '		6.4	6.7	MHz
	30 dB	BW ₃₀			7.2	7.5	MHz
Passband Minimum Insertion Loss (including the matching	ng network) at f _C	IL _{MIN}			15	18	dB
Amplitude Ripple, f _C ± 1.85 MHz					0.7	1.3	dB _{P-P}
Attenuation Relative to Minimum Insertion Loss:	50.00 to 74.39 MHz			39	42		dB
	74.39 to 75.99 MHz			33	38		dB
	85.21 to 86.50 MHz			30	38		dB
	86.50 to 91.50 MHz			35	40		dB
	91.50 to 100.0 MHz			43	46		dB
Group Delay Ripple					40	150	ns _{P-P}
Source Impedance, Differential				2	27 ohms or 200 o	ohms	
Load Impedance, Differential				1	K ohms or 1.5K	ohms	
Case Style			6	SMP-03 7 x 5 mm Nominal Footprint		print	
Lid Symbolization (YY=year, WW=week, S=shift) See note 4					RFM SF21	43B YYWWS	

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

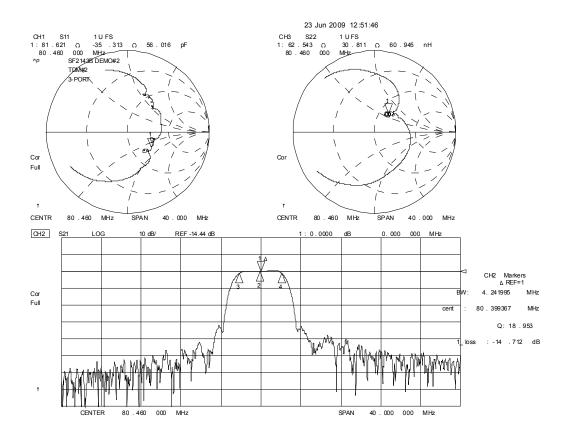
- Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
- Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
- Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
 "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
- The design, manufacturing process, and specifications of this filter are subject to change. Tape and Reel Standard ANSI / EIA 481. 5. 6.
- Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that US and international patents may apply.

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TDM1 Amplitude and Impedance Plots

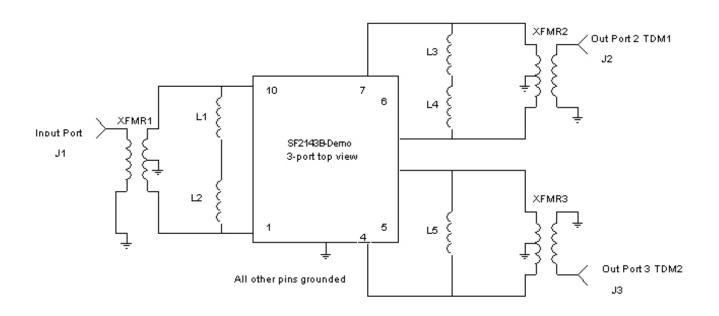


TDM2 Amplitude and Impedance Plots



Test Circuit

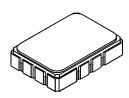
SF2143B Demo Board



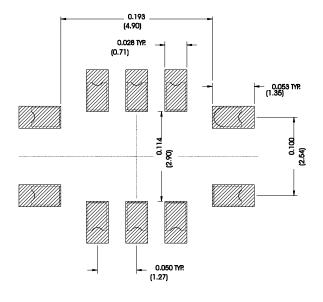
J1-J3	500-0248-002 4 hole flange SMA connecto
PCB	400-1768-001 Gold 7×5 mm pkg PCB
XFMR2, XFMR3	501-0912-004 16:1 Transformer
XFMR1	501-0912-001 4:1 Transformer
L1	501-0782-101 100nH 0805 Ind
L2	501-0782-270 27nH 0805 Ind
L3	501-0782-390 390nH 0805 Ind
L4	501-0782-120 12nH 0805 Ind
L5	501-0782-331 330 nH 0805 Ind

SMP-03 Case

10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



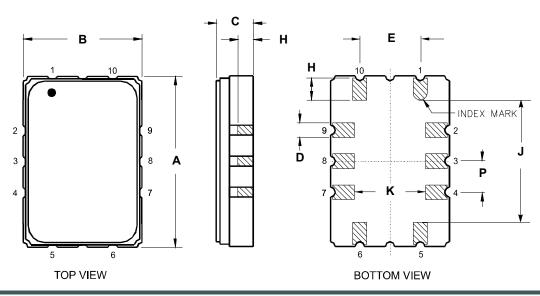
Case Dimensions

Dimension		mm			Inches	
Dilliension	Min	Nom	Max	Min	Nom	Max
Α	6.80	7.00	7.20	0.268	0.276	0.283
В	4.80	5.00	5.20	0.189	0.197	0.205
С	-	1.65	2.00	-	0.065	0.079
D	0.47	0.60	0.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
Н	0.87	1.00	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
Р	1.14	1.27	1.40	0.045	0.050	0.055

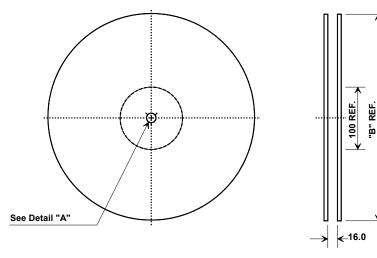
Electrical Connections

	Connection	Terminals
Port 1	Input	1
Port	Input	10
Port 2	Output TDM1	6
POIL 2	Output TDM1	7
Port 3	Output TDM2	4
Port 3	Output TDM2	5
	Ground	All others

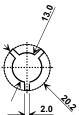
Materials				
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al ₂ O ₃ Ceramic			
Pb Free				



Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	Qualitity Fel Neel
7	178	500
13	330	2000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions				
Ао	5.5 mm			
Во	7.5 mm			
Ko	2.0 mm			
Pitch	8.0 mm			
W	16.0 mm			

